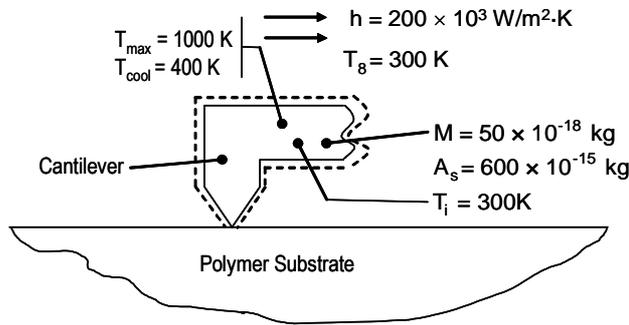


### PROBLEM 5.41

**KNOWN:** Mass and exposed surface area of a silicon cantilever, convection heat transfer coefficient, initial and ambient temperatures.

**FIND:** (a) The ohmic heating needed to raise the cantilever temperature from  $T_i = 300 \text{ K}$  to  $T = 1000 \text{ K}$  in  $t_h = 1 \mu\text{s}$ , (b) The time required to cool the cantilever from  $T = 1000 \text{ K}$  to  $T = 400 \text{ K}$ ,  $t_c$  and the thermal processing time ( $t_p = t_h + t_c$ ), (c) The number of bits that can be written onto a  $1 \text{ mm} \times 1 \text{ mm}$  surface area and time needed to write the data for a processing head equipped with  $M$  cantilevers.

**SCHEMATIC:**



**ASSUMPTIONS:** (1) Lumped capacitance behavior, (2) Negligible radiation heat transfer, (3) Constant properties, (4) Negligible heat transfer to polymer substrate.

**PROPERTIES:** Table A.1, silicon ( $\bar{T} = 650 \text{ K}$ ):  $c_p = 878.5 \text{ J/kg}\cdot\text{K}$ .

**ANALYSIS:**

(a) From Problem 5.20 we note that

$$\frac{\theta}{\theta_i} = \exp\left(-\frac{t}{RC}\right) \quad (1)$$

where  $\theta \equiv T - T(\infty)$  and  $T(\infty)$  is the steady-state temperature corresponding to  $t \rightarrow \infty$ ;

$\theta_i = T_i - T(\infty)$ ,  $R = \frac{1}{hA_s}$ , and  $C = Mc_p$ . For this problem,

$$R = \frac{1}{200 \times 10^3 \text{ W/m}^2 \cdot \text{K} \times 600 \times 10^{-15} \text{ m}^2} = 8.33 \times 10^6 \text{ K/W}$$

$$C = 50 \times 10^{-18} \text{ kg} \times 878.5 \text{ J/kg} \cdot \text{K} = 43.9 \times 10^{-15} \text{ J/K}$$

$$R \times C = 8.33 \times 10^6 \text{ K/W} \times 43.9 \times 10^{-15} \text{ J/K} = 366 \times 10^{-9} \text{ s}$$

Therefore, Equation 1 may be evaluated as

Continued...

**PROBLEM 5.41 (Cont.)**

$$\frac{1000 - T(\infty)}{300 - T(\infty)} = \exp\left(-\frac{1 \times 10^{-6} \text{ s}}{366 \times 10^{-9} \text{ s}}\right) = 0.0651$$

hence,  $T(\infty) = 1049\text{K}$ .

At steady-state, Equation 1.12b yields

$$\begin{aligned} \dot{E}_g &= hA_s(T(\infty) - T_\infty) = 200 \times 10^3 \text{ W/m}^2 \cdot \text{K} \times 600 \times 10^{-15} \text{ m}^2 (1049 - 300) \text{ K} \\ &= 90 \times 10^{-6} \text{ W} = 90 \mu\text{W} \end{aligned} \quad <$$

(b) Equation 5.6 may be used. Hence,

$$\frac{\theta}{\theta_i} = \exp\left[-\left(\frac{hA_s}{Mc}\right)t_c\right] \quad \text{where } \theta = T - T_\infty. \text{ Therefore}$$

$$\frac{400 - 300}{1000 - 300} = 0.143 = \exp\left[-\left(\frac{200 \times 10^3 \text{ W/m}^2 \cdot \text{K} \times 600 \times 10^{-15} \text{ m}^2}{50 \times 10^{-18} \text{ kg} \times 878.5 \text{ J/kg} \cdot \text{K}}\right)t_c\right]$$

$$\text{or } t_c = 0.71 \times 10^{-6} \text{ s} = 0.71 \mu\text{s} \quad <$$

$$\text{and } t_p = t_h + t_c = 1.0 \mu\text{s} + 0.71 \mu\text{s} = 1.71 \mu\text{s} \quad <$$

(c) Each bit occupies  $A_b = 50 \times 10^{-9} \text{ m} \times 50 \times 10^{-9} \text{ m} = 2.5 \times 10^{-15} \text{ m}^2$

Therefore, the number of bits on a  $1 \text{ mm} \times 1 \text{ mm}$  substrate is

$$N = \frac{1 \times 10^{-3} \times 1 \times 10^{-3} \text{ m}^2}{2.5 \times 10^{-15} \text{ m}^2} = 400 \times 10^6 \text{ bits} \quad <$$

The total time needed to write the data ( $t_t$ ) is,

$$t_t = \frac{N \times t_p}{M} = \frac{400 \times 10^6 \text{ bits} \times 1.71 \times 10^{-6} \text{ s/bit}}{100} = 6.84 \text{ s} \quad <$$

**COMMENTS:** (1) Lumped thermal capacitance behavior is an excellent approximation for such a small device (2) Each cantilever writes  $N/M = 400 \times 10^6 \text{ bits}/100 \text{ cantilevers} = 400 \times 10^4 \text{ bits/cantilever}$ . With a separation distance of  $50 \times 10^{-9} \text{ m}$ , the total distance traveled is  $50 \times 10^{-9} \text{ m} \times 400 \times 10^4 = 200 \times 10^{-3} \text{ m} = 200 \text{ mm}$ . If the head travels at  $200 \text{ mm/s}$ , it will take 1 second to move the head, providing a total writing and moving time of  $6.84 \text{ s} + 1 \text{ s} = 7.84 \text{ s}$ . The speed of the process is heat transfer-limited.